

## N-Channel Enhancement Mode Power MOSFET

### ● Features

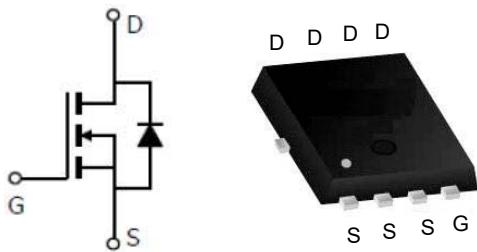
$V_{DS} = 30V$   
 $I_D = 37A$   
 $R_{DS(ON)} \leq 12m\Omega (V_{GS}=10V)$

### ● General Description

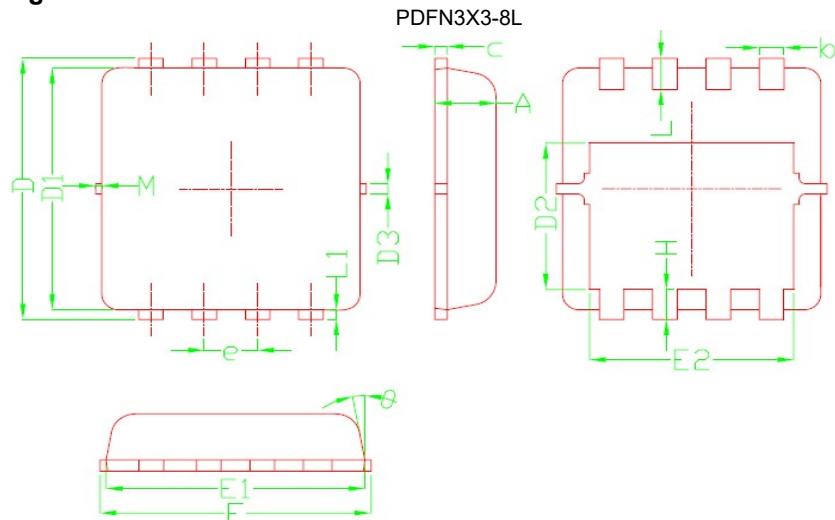
The TNM1230N5X is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The TNM1230N5X meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### ● Pin Configurations



### ● Package Information



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.85	0.027	0.034
b	0.20	0.40	0.007	0.016
c	0.10	0.25	0.004	0.010
D	3.15	3.45	0.124	0.136
D1	2.90	3.20	0.114	0.126
D2	1.54	1.98	0.060	0.080
D3	0.10	0.30	0.004	0.012
E	3.15	3.45	0.124	0.136
E1	3.00	3.25	0.118	0.128
E2	2.29	2.65	0.090	0.104
e	0.65 BSC		0.025 BSC	
H	0.28	0.65	0.011	0.026
$\Theta$	$0^\circ$	$14^\circ$	$0^\circ$	$14^\circ$
L	0.30	0.50	0.012	0.020
L1	0.13		0.005	
M	---	0.15	---	0.006

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● **Absolute Maximum Ratings (@TA=25°C unless otherwise noted)**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DSS</sub>	30	V
Gate Source Voltage	V <sub>GSS</sub>	±20	V
Drain Current (Continuous) *AC	I <sub>D</sub>	37	A
TA=100°C		24	
Drain Current (Pulse) *B	I <sub>DM</sub>	75	A
Power Dissipation	P <sub>D</sub>	26	W
TA=100°C		21	
Operating Temperature/ Storage Temperature	T <sub>J/T<sub>STG</sub></sub>	-55~150	°C
Single Pulse Avalanche Energy	E <sub>AS</sub>	24.2	mJ
Thermal Resistance ,Junction-to-Ambient	R <sub>θJA</sub>	75	°C/W

● **Electrical Characteristics (@TA=25°C unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	--	--	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V	--	--	1	uA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA	1.0	--	2.5	V
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
Drain-Source On-state Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =15A	--	--	12	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	--	--	16.5	mΩ
Diode Forward Voltage	V <sub>SD</sub>	I <sub>SD</sub> =1A, V <sub>GS</sub> =0V	--	--	1	V
<b>Switching</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =15V, I <sub>D</sub> =12A	--	9.8	--	nC
Gate- Source Charge	Q <sub>gs</sub>		--	2.2	--	nC
Gate- Drain Charge	Q <sub>gd</sub>		--	5.5	--	nC
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> =15V, I <sub>D</sub> =20A, R <sub>GEN</sub> =1.5Ω	--	6.4	--	ns
Turn-on Rise Time	t <sub>r</sub>		--	39	--	ns
Turn-off Delay Time	t <sub>d(off)</sub>		--	21	--	ns
Turn-off Fall Time	t <sub>f</sub>		--	4.7	--	ns
<b>Dynamic</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHZ	--	896	--	pF
Output Capacitance	C <sub>oss</sub>		--	126	--	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		--	108	--	pF

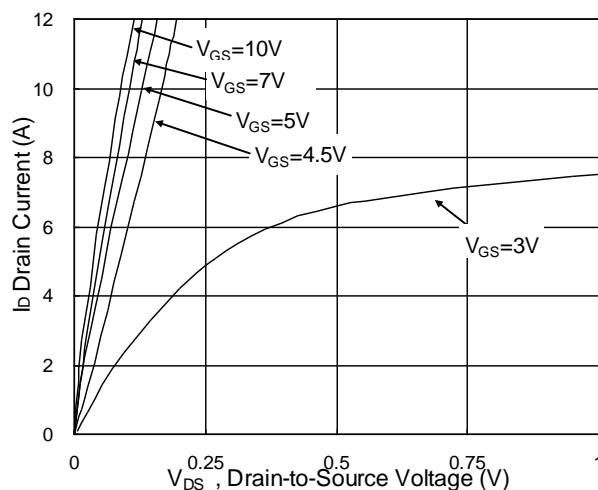
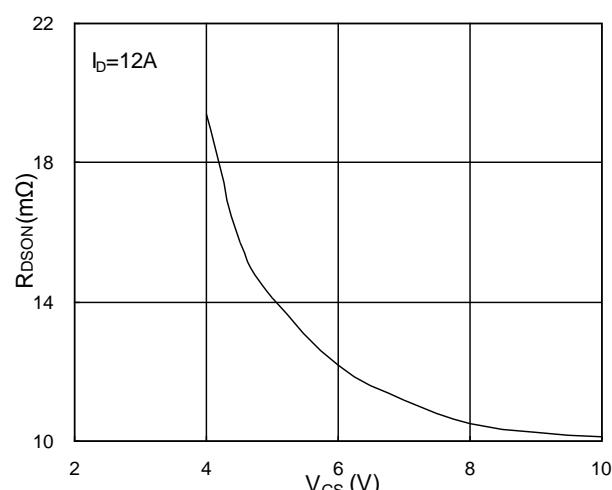
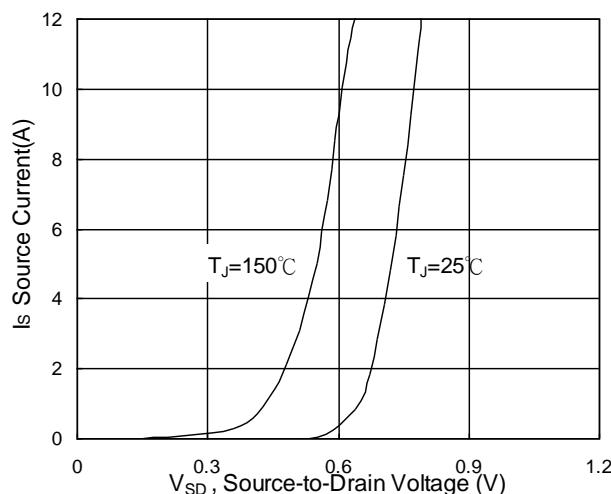
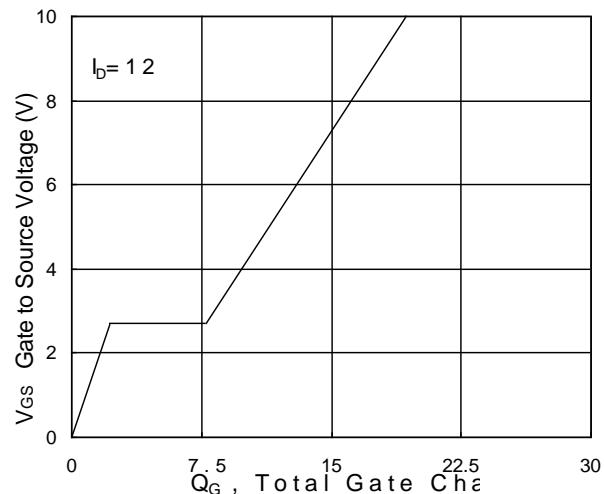
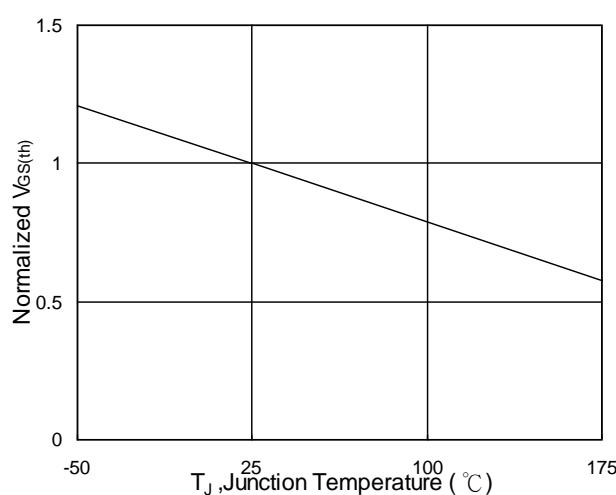
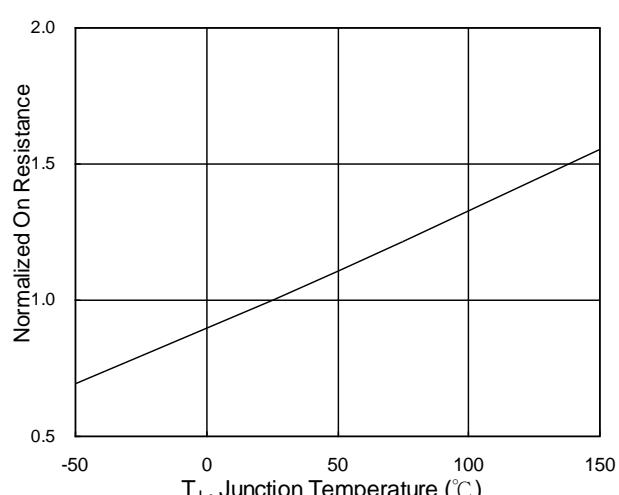
A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR- 4 board with 2oz. Copper, in a still air environment with TA=25C. The value in any given

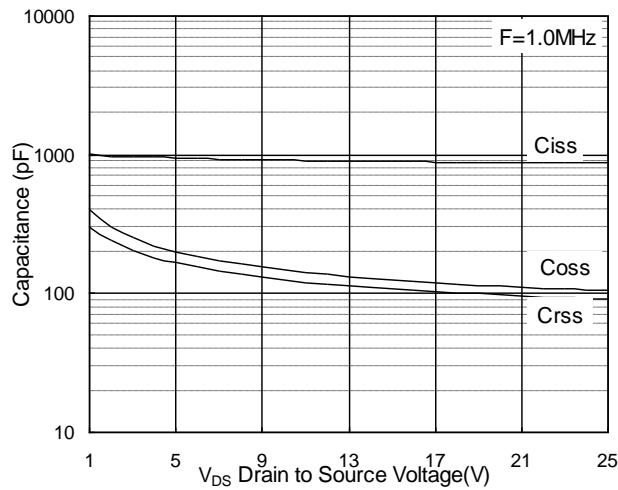
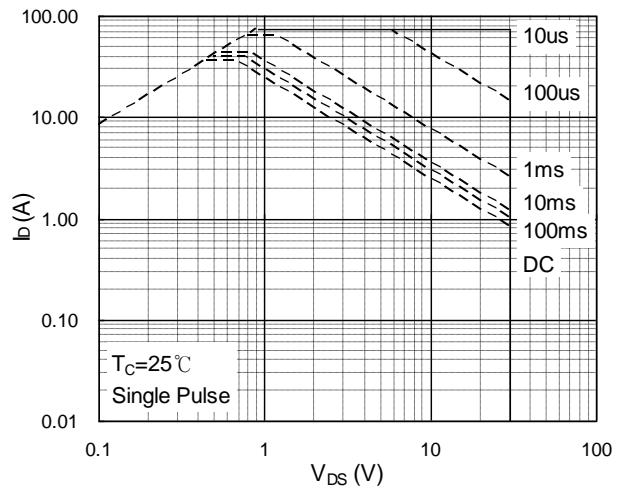
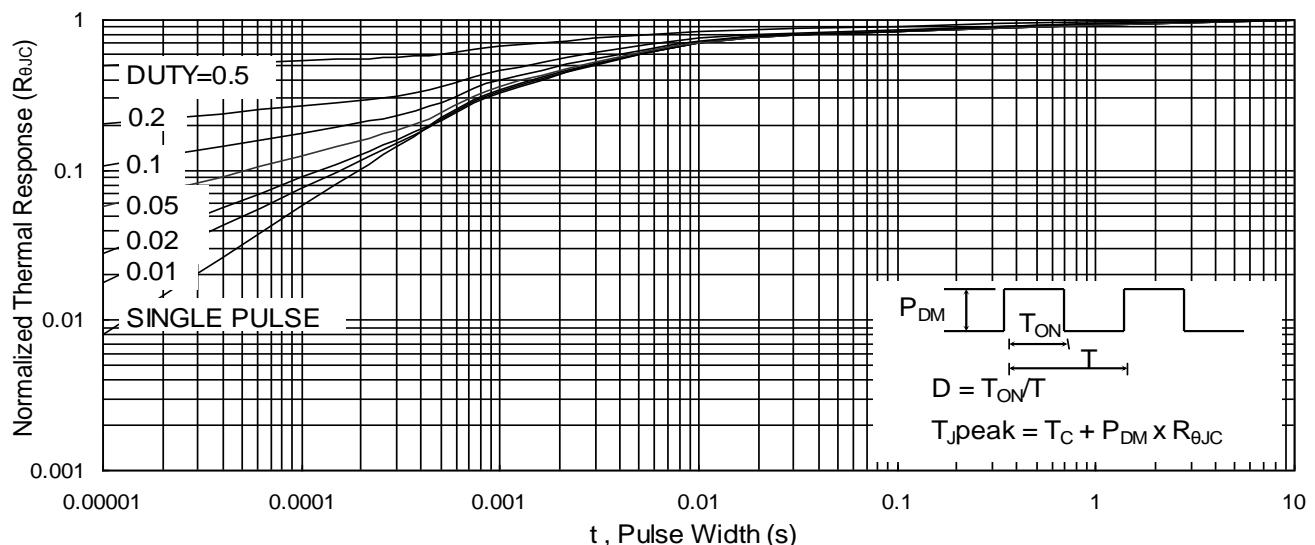
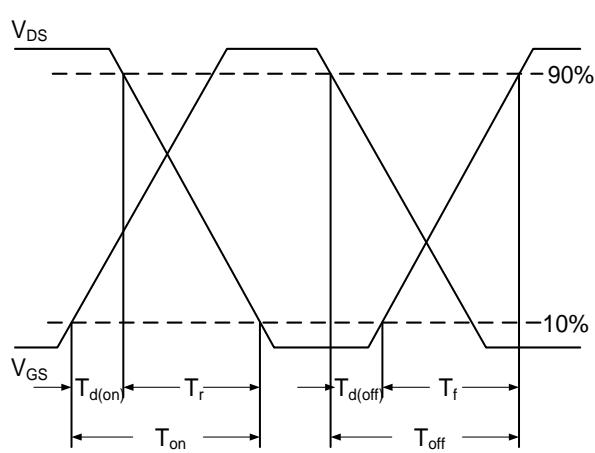
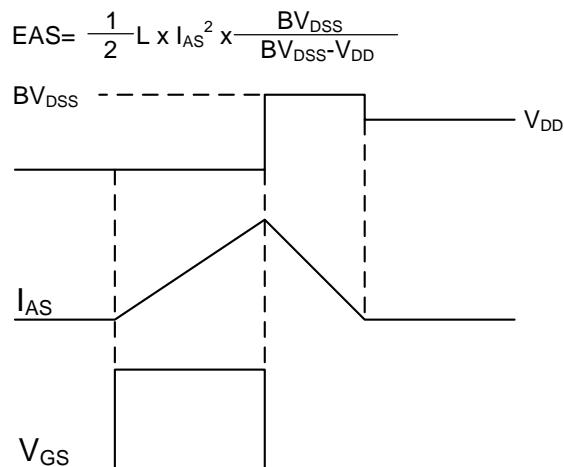
application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature .

C: The current rating is based on the t< 10s junction to ambient thermal resistance rating.

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● **TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs. G-S Voltage**

**Fig.3 Forward Characteristics of Reverse**

**Fig.4 Gate-charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** 

**Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$**

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**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Waveform**

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